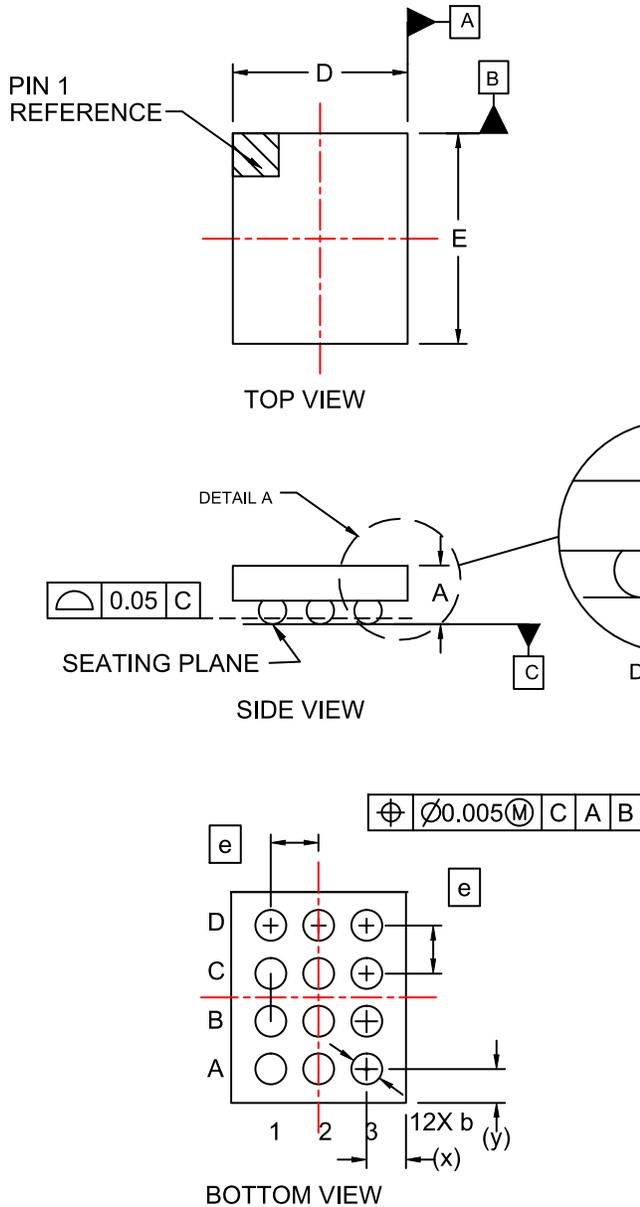




**WLCSP12, 1.41x1.575x0.599**  
CASE 567WM  
ISSUE O

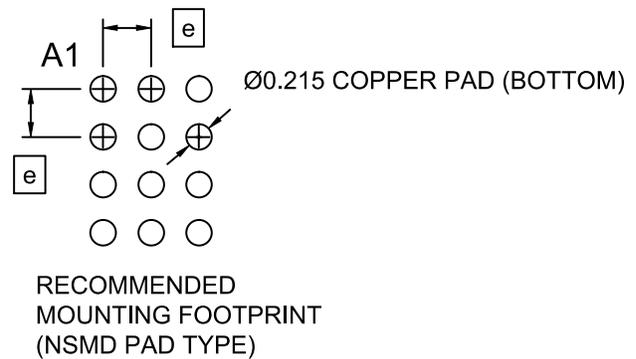
DATE 31 MAY 2018



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.561	0.599	0.637
A1	0.174	0.194	0.214
A2	0.387	0.405	0.423
b	0.240	0.260	0.280
D	1.380	1.410	1.440
E	1.545	1.575	1.605
e	0.40 BSC		
x	0.290	0.305	0.320
y	0.1725	0.1875	0.2025



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